

**ABSTRACT**

The present invention includes: an adhesive material attaching process for attaching a wafer to a thermosetting adhesive material provided on a base film; a dicing-film attaching process for attaching the base film to a dicing film; an IC-chip separating process for cutting the wafer and the thermosetting adhesive material to divide them into IC chips; and a mounting process for attaching, to a carrier, the IC chips having the thermosetting adhesive material attached thereto; wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the adhesive material attaching process.